

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS

1. (Currently Amended) ~~Smart~~ A smart card having a card body (11), at least one recess (12a, 12b) arranged therein for receiving at least one chip module (16) having module connections (17) in the edge region (16a) of the chip module (16) and a conductive structure body embedded in the card body (11) and having body contact connections (13), in particular an antenna having antenna connections which are arranged below the edge region (16a) of the chip module (16), ~~wherein characterized in that~~, with the chip module (16) installed between the module connections (17) on the one hand and the body contact connections (13) on the other hand, adhesive parts (14) ~~made of applied at points and made of elastic~~, conductive material are arranged between the connections (13, 17) characterized in that the adhesive parts (14) are made of elastic material, are applied at points, are cured prior to installing the chip module (16), with pressure being applied to produce a contact.
2. (Currently Amended) ~~Smart~~ The smart card according to Claim 1, characterized in that the adhesive parts (14) are arranged within cutouts (15) which are arranged in the card body (11) below the edge region (16a) of the chip module (16) and at the bottom terminate with the body contact connections (13).
3. (Currently Amended) ~~Smart~~ The smart card according to Claim 2, characterized in that the cutouts (15) have a volume size that is sufficient to completely receive the adhesive parts (14) under the application of pressure.
4. (Currently Amended) ~~Smart~~ The smart card according to Claim 2, characterized in that in the direction of the card body thickness the cutouts (15) have height dimensions (14b) that are smaller than the height (14, 14b) of the adhesive parts (14) applied at points, without the application of pressure.

5. (Currently Amended) ~~Smart~~ The smart card according to Claim 1, characterized in that the adhesive parts (14) form a resilient buffer in order to produce a permanent contact between the chip module connections (13) and body contact connections (17) following installation of the chip module (11) ~~as a resilient buffer~~.

6. (Currently Amended) ~~Smart~~ The smart card according to Claim 1, characterized in that the adhesive parts (14) primarily act along the card body thickness as a resilient buffer.

7. (Currently Amended) ~~Method~~ A method of producing smart cards having a card body (11), at least one recess (12a, 12b) arranged therein for receiving at least one chip module (16) having module connections (17) in the edge region (16a) of the chip module (16) and a conductive structure body embedded in the card body (11) and having body contact connections (13), in particular an antenna having antenna connections which are arranged below the edge region (16a) of the chip module (16), characterized in that, prior to installation of the chip module (11), adhesive parts (14) made of elastic, conductive material are applied at points to the body contact connections (13) and/or the module connections (17) and cured, and then the chip module (11) is installed in the card body (11) with pressure being applied to the adhesive parts (14) made of elastic material.

8. (Currently Amended) ~~Method~~ The method according to Claim 7, characterized in that, prior to installation of the chip module (11), the adhesive parts (14) are applied so as to be about 0.05 to 0.15 mm higher than upper edge regions (15a) of cutouts (15) arranged in the card body, which cutouts are designed to receive the adhesive parts (14).